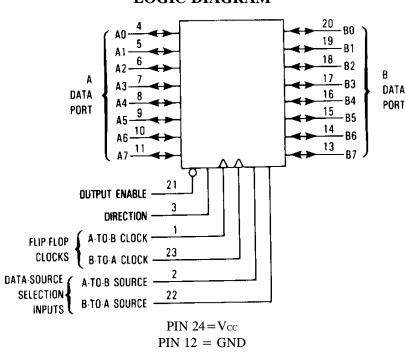
IN74ACT651

Octal 3-State Bus Transceivers and D Flip-Flops High-Speed Silicon-Gate CMOS

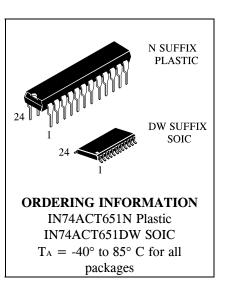
The IN74ACT651 is identical in pinout to the LS/ALS651, HC/HCT651. The IN74ACT651 may be used as a level converter for interfacing TTL or NMOS outputs to High Speed CMOS inputs.

These devices consists of bus transceiver circuits, D-type flipflop, and control circuitry arranged for multiplex transmission of data directly from the data bus or from the internal storage registers. Direction and Output Enable are provided to select the read-time or stored data function. Data on the A or B Data bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock pins (A-to-B Clock or B-to-A Clock) regardless of the select or enable or enable control pins. When A-to-B Source and B-to-A Source are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling Direction and Output Enable. In this configuration each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines will remain at its last state.

- The IN74ACT651 has inverted outputs.
- TTL/NMOS Compatible Input Levels
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 to 5.5 V
- Low Input Current: 1.0 μA; 0.1 μA @ 25°C
- Outputs Source/Sink 24 mA







PIN ASSIGNMENT

	A-TO-B CLOCK	□ 1 ●	24	þ	V _{CC}
	A-TO-B DURCE	[2	23	þ	B-TO-A CLOCK
DIRE	CTION	Γз	22	þ	B-TO-A SOURCE
	A0	Γ4	21	þ	OUTPUT ENABLE
	A1	[5	20	Þ	B0
	A2	[6	19	þ	B 1
	A3	[7	18	þ	B2
	A4	[8	17	þ	B3
	A5	[9	16	þ	B4
	A6	[10	15	þ	B5
	A7	[11	14	þ	B6
ATA	GND	[12	13	þ	B7

Symbol	Parameter	Value	Unit
Vcc	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
Vin	DC Input Voltage (Referenced to GND)	-0.5 to Vcc +0.5	V
Vout	DC Output Voltage (Referenced to GND)	-0.5 to Vcc +0.5	V
Iin	DC Input Current, per Pin	±20	mA
Iout	DC Output Sink/Source Current, per Pin	±50	mA
Icc	DC Supply Current, Vcc and GND Pins	±50	mA
PD	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
Tstg	Storage Temperature	-65 to +150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

MAXIMUM RATINGS^{*}

*Maximum Ratings are those values beyond which damage to the device may occur.

Functional operation should be restricted to the Recommended Operating Conditions.

+Derating - Plastic DIP: - 10 mW/°C from 65° to $125^{\circ}C$

SOIC Package: : - 7 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
Vcc	DC Supply Voltage (Referenced to GND)	4.5	5.5	V
VIN, VOUT	DC Input Voltage, Output Voltage (Referenced to GND)	0	Vcc	V
Tı	Junction Temperature (PDIP)		140	°C
TA	Operating Temperature, All Package Types	-40	+85	°C
Іон	Output Current - High		-24	mA
Iol	Output Current - Low		24	mA
tr, tf	Input Rise and Fall Time *Vcc =4.5 V(except Schmitt Inputs)Vcc =5.5 V	0 0	10 8.0	ns/V

 $\overline{V_{IN}}$ from 0.8 V to 2.0 V

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range $GND \leq (V_{IN} \text{ or } V_{OUT}) \leq V_{CC}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or $V_{\rm CC}$). Unused outputs must be left open.



			Vcc	Guarant		
Symbol	Parameter	Test Conditions	v	25 °C	-40°C to 85°C	Unit
Vih	Minimum High- Level Input Voltage	Vout=0.1 V or Vcc-0.1 V	4.5 5.5	2.0 2.0	2.0 2.0	V
Vil	Maximum Low - Level Input Voltage	$V_{OUT}=0.1 V \text{ or } V_{CC}=0.1 V$	4.5 5.5	0.8 0.8	0.8 0.8	V
Vон	Minimum High- Level Output Voltage	$I_{\rm OUT} \le -50~\mu A$	4.5 5.5	4.4 5.4	4.4 5.4	V
		$V_{IN} = V_{IH}$ or V_{IL} IoH = -24 mA IoH = -24 mA	4.5 5.5	3.86 4.86	3.76 4.76	
Vol	Maximum Low- Level Output Voltage	$I_{OUT} \le 50 \ \mu A$	4.5 5.5	$\begin{array}{c} 0.1 \\ 0.1 \end{array}$	0.1 0.1	V
		$V_{IN} = V_{IH}$ or V_{IL} IoL=24 mA IoL=24 mA	4.5 5.5	0.36 0.36	0.44 0.44	
IIN	Maximum Input Leakage Current	V _{IN} =V _{CC} or GND	5.5	±0.1	±1.0	μΑ
ΔI CCT	Additional Max. Icc/Input	V _{IN} =V _{CC} - 2.1 V	5.5		1.5	mA
Ioz	Maximum Three- State Leakage Current	$V_{I}(OE) = V_{IH} \text{ or } V_{IL}$ $V_{I} = V_{CC} \text{ or } GND$ $V_{O} = V_{CC} \text{ or } GND$	5.5	±0.6	±6.0	μΑ
Іонд	+ Minimum Dynamic Output Current	Vold=1.65 V Max	5.5		75	mA
Іонд	+Minimum Dynamic Output Current	V _{OHD} =3.85 V Min	5.5		-75	mA
Icc	Maximum Quiescent Supply Current (per Package)	V _{IN} =V _{CC} or GND	5.5	8.0	80	μΑ

DC ELECTRICAL CHARACTERISTICS(Voltages Referenced to GND)

*All outputs loaded; thresholds on input associated with output under test.

+Maximum test duration 2.0 ms, one output loaded at a time.



		(
Symbol	Parameter	25	°C	-40°C	Unit			
		Min	Max	Min	Max			
t plh	Propagation Delay, A-to-B Clock or B-to-A Clock to A or B Data Port (Figure 1)	4.0	14.5	3.5	16.5	ns		
t phl	Propagation Delay, A-to-B Clock or B-to-A Clock3.514.53.016.5to A or B Data Port (Figure 1)							
t plh	Propagation Delay, Input A to Output B or Input B to Output A (Figures 2,3)	2.5	11.5	2.0	13.0	ns		
t phl	Propagation Delay, Input A to Output B or Input B to Output A (Figures 2,3)	2.5	11.5	2.0	13.0	ns		
t plh	Propagation Delay, A-to-B Source or B-to-A2.512.02.013.5Source to A or B Data Port (Figure 4)11111							
t phl	Propagation Delay, A-to-B Source or B-to-A Source to A or B Data Port (Figure 4)	12.0	2.5	13.5	ns			
tрzн	Propagation Delay, Output Enable to A Data Port (Figure 5)							
t pzl	Propagation Delay, Output Enable to A Data Port (Figure 5)	2.5	11.5	2.0	13.0	ns		
t phz	Propagation Delay, Output Enable to A Data Port (Figure 5)	3.0	13.0	2.5	14.0	ns		
t plz	Propagation Delay, Output Enable to A Data Port (Figure 5)	2.5	12.5	2.0	14.0	ns		
t pzh	Propagation Delay, Direction to B Data Port (Figure 6)	2.5	12.0	2.0	13.5	ns		
t pzl	Propagation Delay, Direction to B Data Port (Figure 6)	2.5	12.0	2.0	13.5	ns		
t phz	Propagation Delay, Direction to B Data Port (Figure 6)	3.5	13.5	3.0	14.5	ns		
t plz	Propagation Delay, Direction to B Data Port (Figure 6)	3.0 13.5 2.5 15.0				ns		
Cin	Maximum Input Capacitance	4	.5	4	pF			
Cout	Input/Output Capacitance	15 15			pF			

AC ELECTRICAL CHARACTERISTICS ($V_{CC}=5.0 \text{ V} \pm 10\%$, $C_L=50 \text{pF}$, Input tr=tf=3.0 ns)

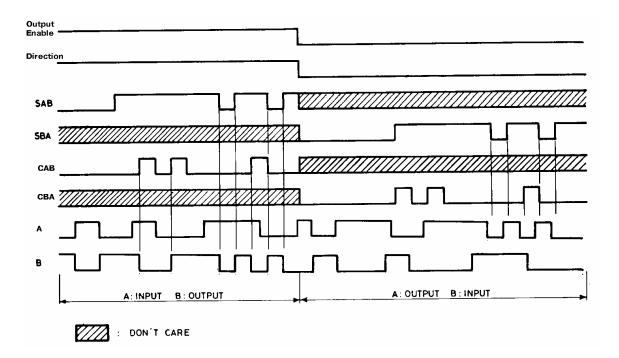




		Guarantee			
Symbol	Parameter	25 °C	-40°C to 85°C	Unit	
tsu	Minimum Setup Time, A or B Data Port to A-to-B Clock or B-to-A Clock (Figure 7)	7.0	8.0	ns	
th	Minimum Hold Time, A-to-B Clock or B-to-A Clock to A or B Data Port (Figure 7)	2.5	2.5	ns	
tw	Minimum Pulse Width, A-to-B Clock or B-to-A Clock (Figure 7)	6.0	7.0	ns	

TIMING REQUIREMENTS (V_{CC} =5.0 V ± 10 %, CL=50pF,Input tr=tf=3.0 ns)





IN74ACT651

	-	-	-	-	ŀ	FUNCTION	N TABLE	
Dir.	OE	CAB	CBA	SAB	SBA	А	В	FUNCTION
						INPUTS	INPUTS	Both the A bus and the B bus are inputs.
L	Н	X	Х	Х	Х	Z	Z	The output functions of the A and B bus are disabled.
		_ F	_	Х	Х	INPUTS	INPUTS	Both the A and B bus are used for inputs to the internal flip-flops. Data at the bus will be stored on low to high transition of the clock inputs.
						OUTPUTS	INPUTS	The A bus are outputs and the B bus are inputs.
		X*	Х	X	L	H L	L H	The data at the B bus are displayed at the A bus.
L	L	X*	₽	Х	L	H L	L H	The data at the B bus are displayed at the A bus. The data of the B bus are stored to the internal flip-flops on low to high transition of the clock pulse.
		X*	X	X	Н	Qn	Х	The data stored to the internal flip-flops, are displayed at the A bus.
		X*	<u> </u>	X	Н	L H	H L	The data at the B bus are stored to the internal flip-flops on low to high transition of the clock pulse. The states of the internal flip-flops output directly to the A bus.
						INPUTS	OUTPUTS	The A bus are inputs and the B bus are outputs.
		X	X *	L	Х	H L	L H	The data at the A bus are displayed at the B bus.
Н	Н	<u> </u>	X*	L	X	H L	L H	The data at the B bus are displayed at the A bus. The data of the B bus are stored to the internal flip-flops on low to high transition of the clock pulse.
		Х	\mathbf{X}^*	Н	Х	Х	Qn	The data stored to the internal flip-flops are displayed at the B bus.
			X*	Н	X	H L	L H	The data at the A bus are stored to the internal flip-flops on low to high transition of the clock pulse. The states of the internal flip-flops output directly to the B bus.
						OUTPUTS	OUTPUTS	Both the A bus and the B bus are outputs
Н	L	X	Х	Н	Н	Qn	Qn	The data stored to the internal flip-flops are displayed at the A and B bus respectively.
		_	_€	Н	Н	Qn	Qn	The output at the A bus are displayed at the B bus, the output at the B bus are displayed at the A bus respec.

FUNCTION TABLE

X : DON'T CARE

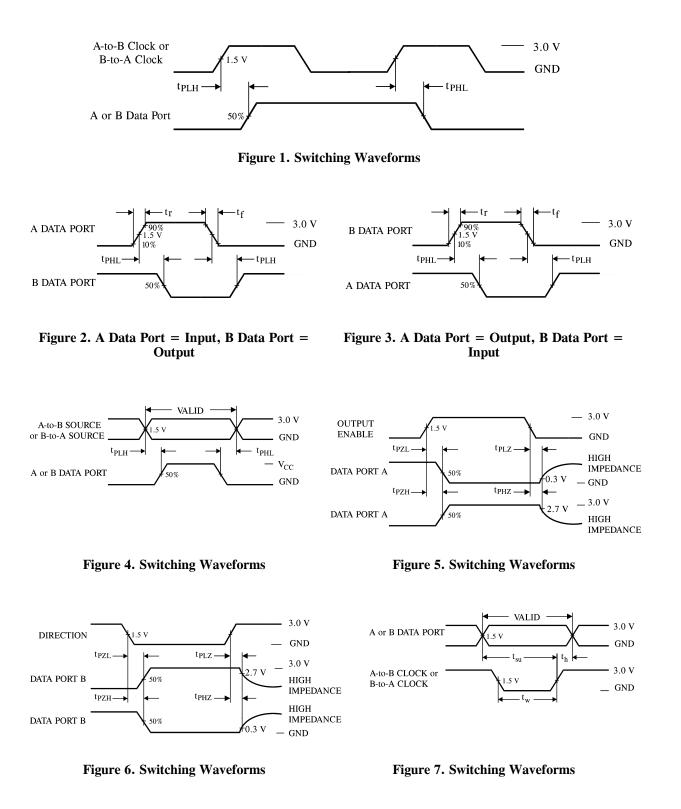
Z : HIGH IMPEDANCE

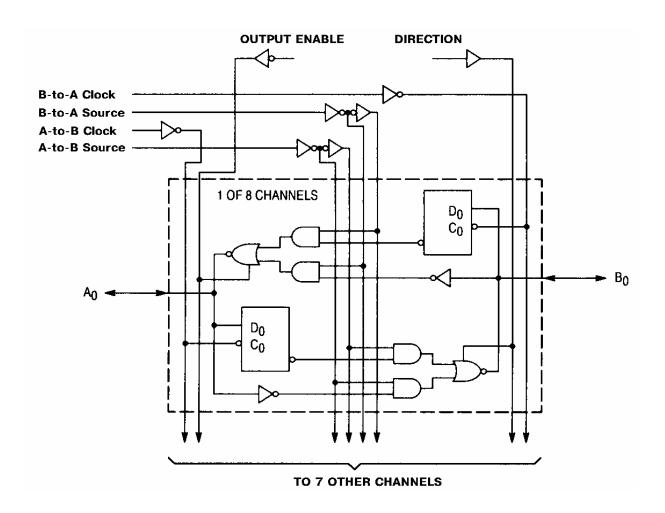
Qn : THE DATA STORED TO THE INTERNAL FLIP-FLOPS BY MOST RECENT LOW TO HIGH TRANSITION OF THE CLOCK INPUTS

 * : THE DATA AT THE A AND B BUS WILL BE STORED TO THE INTERNAL FLIP-FLOPS ON EVERY LOW TO TRANSITION OF THE CLOCK INPUTS









EXPANDED LOGIC DIAGRAM

